



MATERIEL THERMIQUE & ELECTRONIQUE

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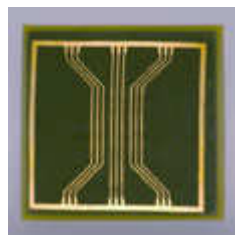
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CTE-Matched Solutions: Better Heat Sink Performance

CTE-matched thermal solutions from Thermacore give you precise control with compact size and light weight, thanks to leading-edge technology.



Meet the challenges of effectively cooling today's unprecedented, high-heat-flux electronics components with coefficient of thermal expansion (CTE)-matched solutions, featuring a heat sink base attached directly to silicon. CTE matching allows designers to dissipate dramatically increased heat fluxes at the die level, while minimising significant thermal resistances and increasing heat sink efficiency. With the high thermal conductivity of k-Core[®] high encapsulated in a tailorable CTE material, semiconductor chips can run cooler in high-performance electronic packages. As a result, these packages can handle higher power densities allowing higher overall power or smaller package size.